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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/652,348	08/29/2003	Franklin J. Wall JR.	LUM-03-06-10	1306
32566 7	05/18/2006		EXAM	INER
PATENT LAW GROUP LLP			FARAHANI, DANA	
2635 NORTH FIRST STREET				
SUITE 223			ART UNIT	PAPER NUMBER
SAN JOSE, C	A 95134		2891	

DATE MAILED: 05/18/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

PTO-90C (Rev. 10/03)

			H:			
		Application No.	Applicant(s)			
		10/652,348	WALL, FRANKLIN J.			
	Office Action Summary	Examiner	Art Unit			
		Dana Farahani	2891			
Period fo	The MAILING DATE of this communication app or Reply	pears on the cover sheet with the	correspondence address			
WHI( - Exte after - If NO - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DONA IN THE MAIL	ATE OF THIS COMMUNICATION  36(a). In no event, however, may a reply be will apply and will expire SIX (6) MONTHS from the application to become ABANDON	DN. timely filed m the mailing date of this communication. IED (35 U.S.C. § 133).			
Status						
1)⊠	Responsive to communication(s) filed on 23 Fe	ebruary 2006.				
2a) <u></u> ☐	This action is <b>FINAL</b> . 2b)⊠ This action is non-final.					
3)□	Since this application is in condition for allowa					
	closed in accordance with the practice under E	Ex parte Quayle, 1935 C.D. 11,	453 O.G. 213.			
Disposit	ion of Claims					
4)⊠	Claim(s) 1-24 is/are pending in the application					
	4a) Of the above claim(s) <u>18-22</u> is/are withdrawn from consideration.					
′	Claim(s) is/are allowed.					
,	Claim(s) <u>1-17,23 and 24</u> is/are rejected.					
	Claim(s) is/are objected to. Claim(s) are subject to restriction and/o	or election requirement				
ا_ا(ه	claim(s) are subject to restriction and/o	or election requirement.				
Applicat	ion Papers					
, —	The specification is objected to by the Examine					
10)	The drawing(s) filed on is/are: a) acc					
	Applicant may not request that any objection to the					
11)□	Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Ex					
	under 35 U.S.C. § 119					
•	Acknowledgment is made of a claim for foreign	nriority under 35 H.S.C. & 119/	(a)-(d) or (f)			
	□ All b) □ Some * c) □ None of:	i priority dilder 55 6.6.6. § 116(	a) (a) 51 (1).			
1. Certified copies of the priority documents have been received.						
	2. Certified copies of the priority documents have been received in Application No					
	3. Copies of the certified copies of the prior	ority documents have been recei	ived in this National Stage			
	application from the International Burea					
* See the attached detailed Office action for a list of the certified copies not received.						
			•			
Attachme			(DTO 442)			
	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948)	4) Interview Summa Paper No(s)/Mail				
3) 🔯 Info	rmation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) er No(s)/Mail Date <u>8/29/03</u> .	) 5) Notice of Informa 6) Other:	l Patent Application (PTO-152)			

# Claim Rejections - 35 USC § 103

DETAILED ACTION

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1, 3-12, 14-17, 23, and 24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shie et al, hereinafter Shie (US Patent 6,480,389), newly cited.

Regarding claims 1, 7-9, 16, 17, and 23, Shie discloses, fig. 1, a structure comprising: a semiconductor light emitting device (LED) 20;

a substrate comprising a ceramic core 50 and at least one copper layer 10 overlying the core;

wherein the LED is electrically connected to the at least one copper layer and wherein a path from the at least one copper layer to the ceramic core is thermally conductive.

Shie does not expressly disclose the copper layer having a thickness of at least 4, or between 4-24 mils. However, it would have been obvious to one of ordinary skill in the art at the time of the invention to make the layer having such a large thickness in order to adjust the heat radiating properties of the layer.

Regarding claim 3, although Shie does not expressly disclose the core comprises a material selected from the group of aluminum oxide/nitride and silicon nitride, it discloses that the ceramic core is a PCB aluminum based (see col. 3, line 1). Since PCB's are normally isolative and aluminum oxide/nitride are the most common form of aluminum based insulators, it

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is very likely that the core is in fact aluminum oxide/nitride. Assuming, arguendo, that the ceramic core 50 is not aluminum oxide/nitride, it would have been obvious to one of ordinary skill in the art at the time of the invention to make the core as aluminum oxide/nitride, since it is suggested in the reference that the core is aluminum based, and aluminum oxide and aluminum nitride are the most common form of aluminum based insulators.

Regarding claim 4, at least one lead 52 is connected to the substrate.

Regarding claim 5, at least one solder pad 12 is connected to the substrate.

Regarding claim 6, at least one terminated wire, any of the wires shown in the figure, is connected to the substrate.

Regarding claim 10, a second substrate, the substrate comprising layers 14 and 15b, is disposed between the LED and the first substrate.

Regarding claim 11, the second substrate comprises at least one metal bonding pad 15b and an insulating layer 14.

Regarding claim 12, the insulating layer is Alumina (see col. 3, line 4).

Regarding claim 14, a base 60 is connected to the substrate.

Regarding claim 15, a lens, the top portion of the housing 40, is disposed over the LED.

Regarding claim 24, copper layer 12 can be considered as part of the copper layer 10, and layer 51 part of the ceramic core, in which case the copper layer directly contacts the core.

3. Claims 2 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shie as applied to claim 1 above, and further in view of Applicant's Admitted Prior Art (AAPA), newly cited.

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Shie discloses the limitations in the claims, but does not disclose the light-emitting element has a III-nitride light-emitting layer, and that the second substrate comprises a silicon integrated circuit.

AAPA discloses that III-nitride light emitters are known and used in the art (paragraph 2) and further discloses a silicon ESD protection integrated circuit 2 is formed beneath the LED 1 (see fig. 1, and paragraph 3). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to use a III-nitride type light emitter layer, in order to emit any color of desired light (i.e. UV-red) or combinations thereof (e.g. white), and use a silicon integrated circuit between the LED and the first substrate of the Shie's structure in order to protect the chip therein from electrostatic discharge.

### **Product-by-Process Limitations**

A comparison of the recited process with the prior art process does NOT serve to resolve the issue concerning patentability of the product. *In re Fessman*, 489 F2d 742, 180 USPQ 324 (CCPA 1974). Whether a product is patentable depends on whether it is known in the art or it is obvious, and is not governed by whether the process by which is made is patentable. *In re Klug*, 333 F2d 905, 142 USPQ 161 (CCPA 1964). In an ex parte case, product by process claims are not constructed as being limited to the product formed by the specific process recited. In re Hirao et al., 535 F2d 67, 190 USPQ 15, see footnote 3 (CCPA 1976). Therefore, in claims 7 and 17, the process of bonding (or in case of claim 7, the method which is used in bonding) the copper layer to the core is given less patentable weight.

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## Response to Arguments

4. Applicant's arguments with respect to claims 1-17, 23 and 24 have been considered but are moot in view of the new ground(s) of rejection.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dana Farahani whose telephone number is (571)272-1706. The examiner can normally be reached on M-F 9:00AM - 6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on (571)272-1722. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

D. Farahani

PRIMARY EXAMINER